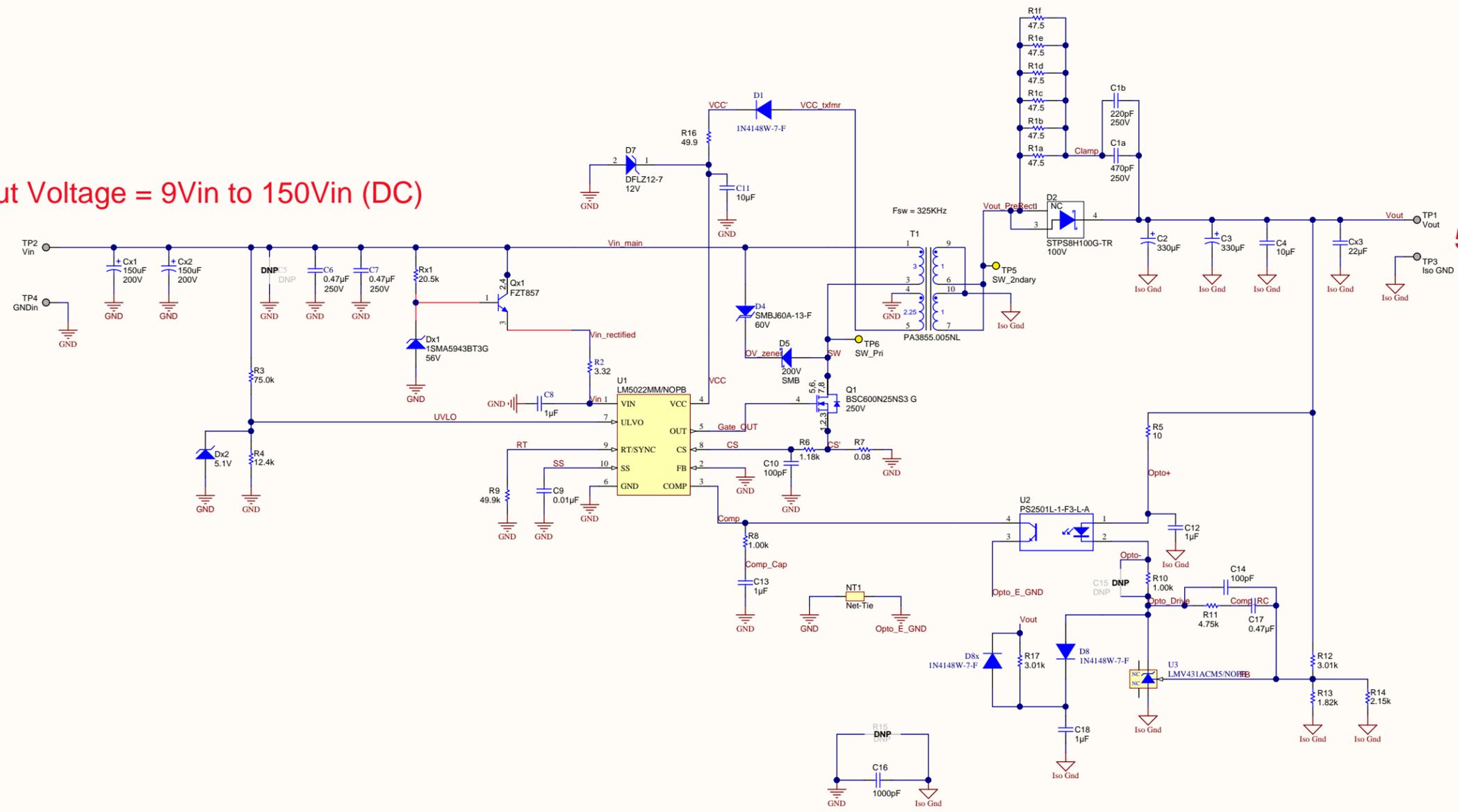


Input Voltage = 9Vin to 150Vin (DC)

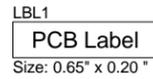
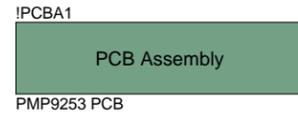
5Vout @ 4A Max.



**\*NOTES:**

1. All components containing an "x" suffix were added to the design after the PCB was fabricated. These components do not have placeholders on the PCB.
2. R1a, R1b, R1c, R1d, R1e, and R1f can be replaced by a single resistor of around 8ohms, rated at about 1.5W.
3. C1a and C1b can be replaced by a single 680pF capacitor (use C0G or NP0 type, at least 100V-rated or higher, 0805 package preferred).
4. RED traces on the schematic signify wiring that was performed as a modification to the original PCB layout. Traces do not exist on the PCB for these nets.
5. Design is built on PMP9253 PCB.

Title		
LM5022 Wide Vin Isolated Flyback Converter		
Size	Number	Revision
c	PMP20196	
Date:	12/4/2017	Sheet of
File:	C:\Users\...PMP20196_Schematic.SchDoc	Drawn By: Hrag Kasparian



Variant/Label Table	
Variant	Label Text
001	

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Orderable: N/A	Designed for:	Mod. Date: 12/4/2017	
TID #: PMP20196	Project Title: LM5022 Isolated Flyback Converter	Sheet: 2 of 2	
Number: PMP20196	Rev: A	Sheet Title: Hardware	http://www.ti.com © Texas Instruments 2016
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By:	File: PMP20196_EVM_Hardware.SchDoc	Contact: http://www.ti.com/support	
Engineer: Hrag Kasparian			

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